Document Title

256Kx36 & 256Kx32 & 512Kx18-Bit Synchronous Pipelined Burst SRAM

Revision History

Rev. No.	History	Draft Date	Remark
0.0	Initial draft	May. 18 . 2001	Preliminary
0.1	1. Delete pass- through	June. 26. 2001	Preliminary
0.2	1. Add x32 org part and industrial temperature part	Aug. 11. 2001	Preliminary
0.3	1. change scan order(1) form 4T to 6T at 119BGA(x18)	Aug. 28. 2001	Preliminary
1.0	1. Final spec release 2. Change I_{SB2} form 50mA to 60mA	Nov. 16. 2001	Final
2.0	Remove tCYC 225MHz(-22)	April. 01. 2002	Final
2.1	1. Delete 119BGA package	April. 04. 2003	Final

8Mb SB/SPB Synchronous SRAM Ordering Information

Org.	Part Number	Mode	VDD	Speed FT ; Access Time(ns) Pipelined ; Cycle Time(MHz)	PKG	Temp
512Kx18	K7B801825B-QC(I)65/75/85	SB	3.3	6.5/7.5/8.5 ns	Q: 100TQFP	C: Commercial Temperature Range I: Industrial Temperature Range
	K7A801800B-QC(I)16/14	SPB(2E1D)	3.3	167/138 MHz		
	K7A801809B-QC(I)25/20	SPB(2E1D)	3.3	250/200 MHz		
	K7A801801B-QC(I)16/14	SPB(2E2D)	3.3	167/138 MHz		
	K7A801808B-QC(I)25/20	SPB(2E2D)	3.3	250/200 MHz		
256Kx32	K7B803225B-QC(I)65/75/85	SB	3.3	6.5/7.5/8.5 ns		
	K7A803200B-QC(I)16/14	SPB(2E1D)	3.3	167/138 MHz		
	K7A803209B-QC(I)25/20	SPB(2E1D)	3.3	250/200 MHz		
	K7A803201B-QC(I)16/14	SPB(2E2D)	3.3	167/138 MHz		
	K7A803208B-QC(I)25/20	SPB(2E2D)	3.3	250/200 MHz		
256Kx36	K7B803625B-QC(I)65/75/85	SB	3.3	6.5/7.5/8.5 ns		
	K7A803600B-QC(I)16/14	SPB(2E1D)	3.3	167/138 MHz		
	K7A803609B-QC(I)25/20	SPB(2E1D)	3.3	250/200 MHz		
	K7A803601B-QC(I)16/14	SPB(2E2D)	3.3	167/138 MHz		
	K7A803608B-QC(I)25/20	SPB(2E2D)	3.3	250/200 MHz		

NOTE : 119BGA is Only Supported with K7A801800B-HC16, K7A803600B-HC16 and K7A803609B-HC20.

256Kx36 & 256Kx32 & 512Kx18-bit Synchronous Pipelined Burst SRAM

FEATURES

- Synchronous Operation.
- 2 Stage Pipelined operation with 4 Burst.
- On-Chip Address Counter.
- Self-Timed Write Cycle.
- On-Chip Address and Control Registers.
- 3.3V+0.165V/-0.165V Power Supply.
- I/O Supply Voltage 3.3V+0.165V/-0.165V for 3.3V I/O or 2.5V+0.4V/-0.125V for 2.5V I/O
- 5V Tolerant Inputs Except I/O Pins.
- Byte Writable Function.
- Global Write Enable Controls a full bus-width write.
- Power Down State via ZZ Signal.
- $\overline{LBO}$ Pin allows a choice of either a interleaved burst or a linear burst.
- Three Chip Enables for simple depth expansion with No Data Contention only for TQFP ; 2cycle Enable, 1cycle Disable.
- Asynchronous Output Enable Control.
- $\overline{ADSP}$, $\overline{ADSC}$, $\overline{ADV}$ Burst Control Pins.
- TTL-Level Three-State Output.
- 100-TQFP-1420A
- Operating in commeical and industrial temperature range.

FAST ACCESS TIMES

PARAMETER	Symbol	-25	-20	Unit
Cycle Time	tCYC	4.0	5.0	ns
Clock Access Time	tCD	2.6	3.1	ns
Output Enable Access Time	tOE	2.6	3.1	ns

GENERAL DESCRIPTION

The K7A803609B, K7A803209B and K7A801809B are 9,437,184-bit Synchronous Static Random Access Memory designed for high performance second level cache of Pentium and Power PC based System.

It is organized as 256K(512K) words of 36(18) bits and integrates address and control registers, a 2-bit burst address counter and added some new functions for high performance cache RAM applications; $\overline{GW}$, $\overline{BW}$, $\overline{LBO}$, ZZ. Write cycles are internally self-timed and synchronous.

Full bus-width write is done by $\overline{GW}$, and each byte write is performed by the combination of $\overline{WEx}$ and $\overline{BW}$ when $\overline{GW}$ is high. And with $\overline{CS_1}$ high, $\overline{ADSP}$ is blocked to control signals.

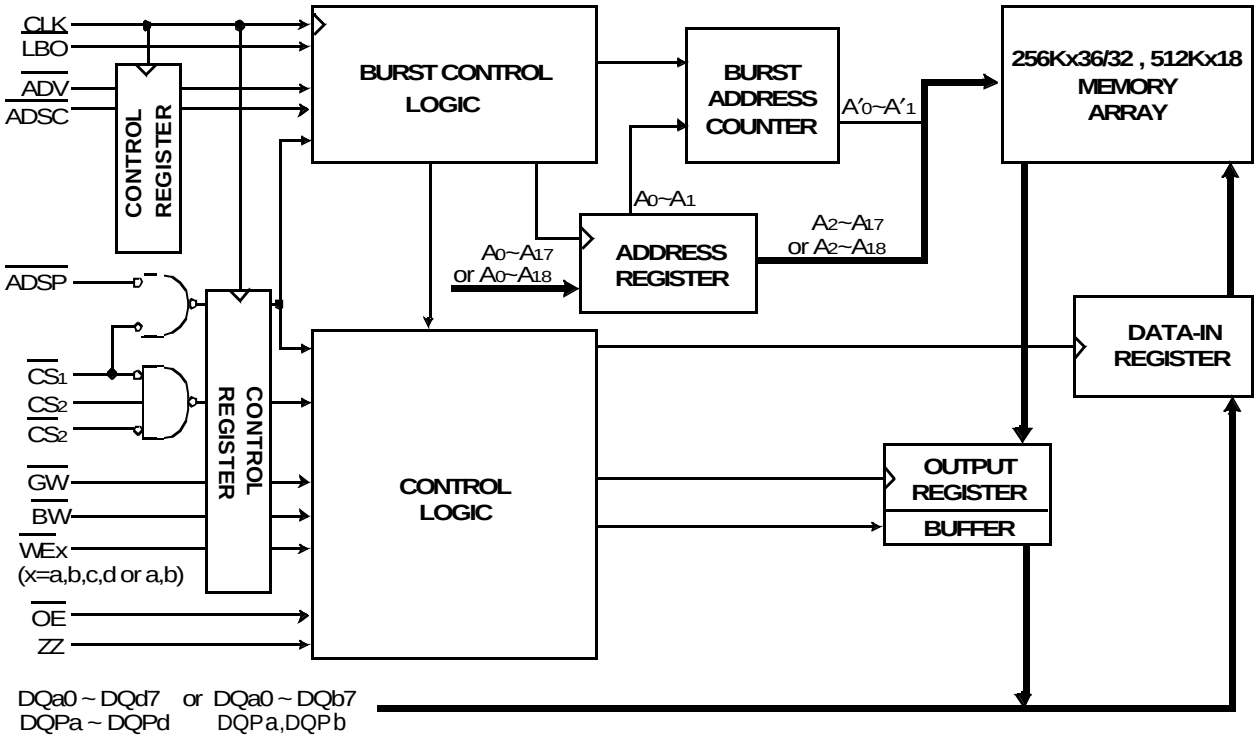
Burst cycle can be initiated with either the address status processor($\overline{ADSP}$) or address status cache controller($\overline{ADSC}$) inputs. Subsequent burst addresses are generated internally in the system's burst sequence and are controlled by the burst address advance($\overline{ADV}$) input.

$\overline{LBO}$ pin is DC operated and determines burst sequence(linear or interleaved).

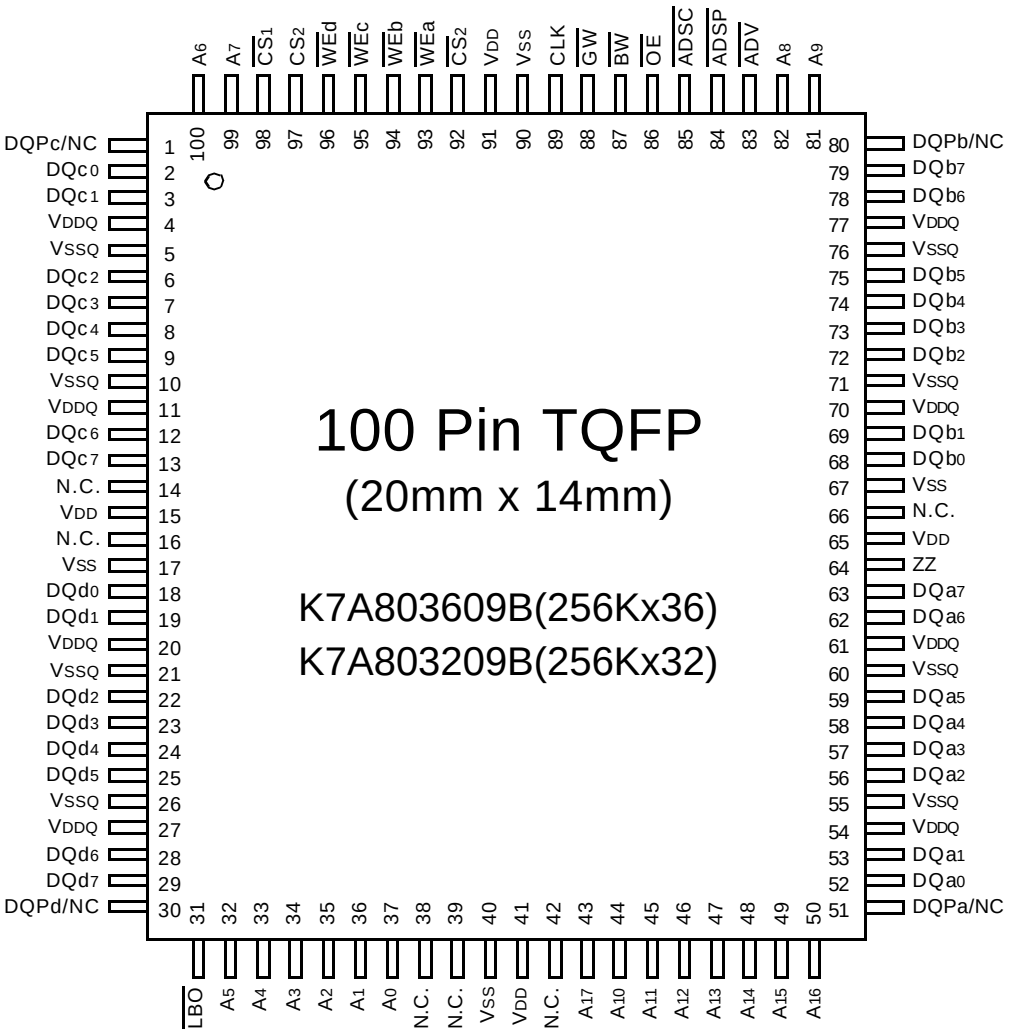
ZZ pin controls Power Down State and reduces Stand-by current regardless of CLK.

The K7A803609B, K7A803209B and K7A801809B are fabricated using SAMSUNG's high performance CMOS technology and is available in a 100pin TQFP and Multiple power and ground pins are utilized to minimize ground bounce.

LOGIC BLOCK DIAGRAM



PIN CONFIGURATION(TOP VIEW)

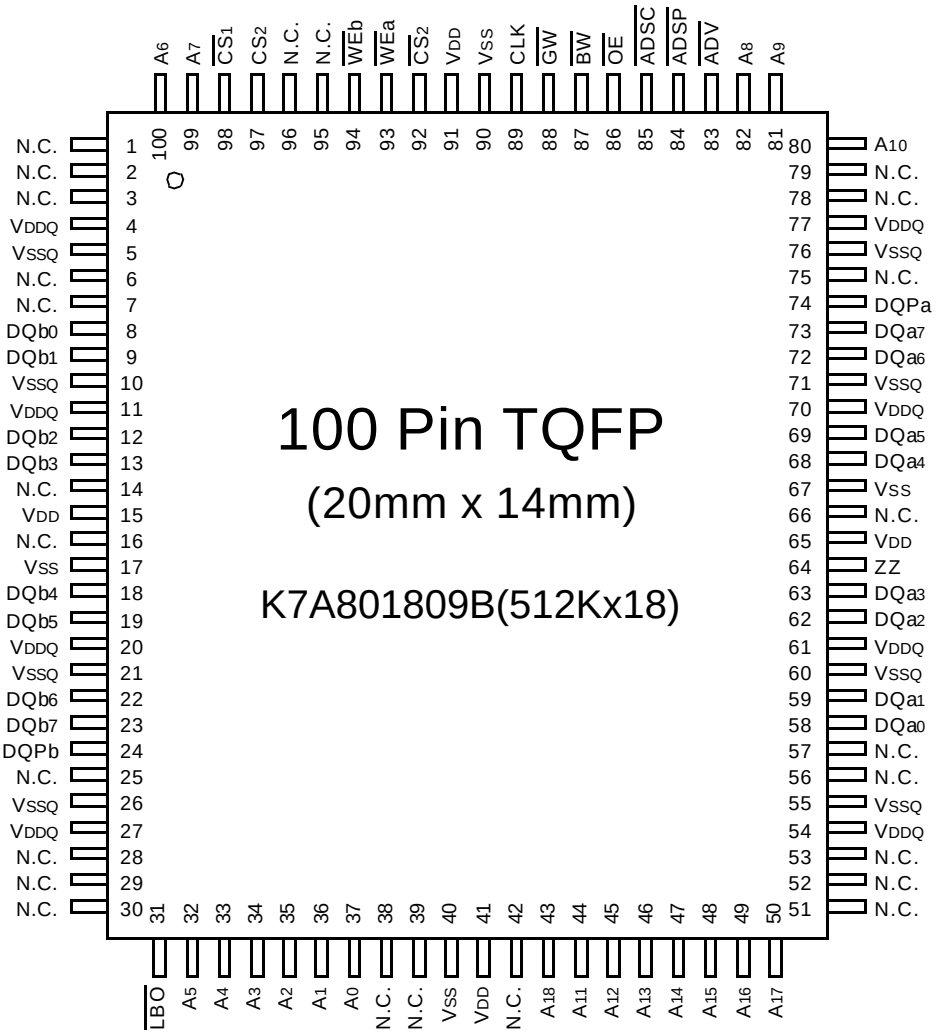


PIN NAME

SYMBOL	PIN NAME	TQFP PIN NO.	SYMBOL	PIN NAME	TQFP PIN NO.
A_0 - A_{17}	Address Inputs	32,33,34,35,36,37,43	V_{DD}	Power Supply(+3.3V)	15,41,65,91
		44,45,46,47,48,49,50	V_{SS}	Ground	17,40,67,90
		81,82,99,100	N.C.	No Connect	14,16,38,39,42,66
$\overline{ADV}$	Burst Address Advance	83			
$\overline{ADSP}$	Address Status Processor	84	DQa_0~a_7	Data Inputs/Outputs	52,53,56,57,58,59,62,63
$\overline{ADSC}$	Address Status Controller	85	DQb_0~b_7		68,69,72,73,74,75,78,79
CLK	Clock	89	DQc_0~c_7		2,3,6,7,8,9,12,13
$\overline{CS_1}$	Chip Select	98	DQd_0~d_7		18,19,22,23,24,25,28,29
CS_2	Chip Select	97	DQPa~Pd		51,80,1,30
$\overline{CS_2}$	Chip Select	92	/NC		
$\overline{WE}$x(x=a,b,c,d)	Byte Write Inputs	93,94,95,96	V_{DDQ}	Output Power Supply (2.5V or 3.3V)	4,11,20,27,54,61,70,77
$\overline{OE}$	Output Enable	86			
$\overline{GW}$	Global Write Enable	88	V_{SSQ}	Output Ground	5,10,21,26,55,60,71,76
$\overline{BW}$	Byte Write Enable	87			
$\overline{ZZ}$	Power Down Input	64			
LBO	Burst Mode Control	31			

Notes : 1. A_0 and A_1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.
2. The pin 42 is reserved for address bit for the 16Mb .
3. DQPa~DQPd are NC for K7A803209B.

PIN CONFIGURATION(TOP VIEW)



PIN NAME

SYMBOL	PIN NAME	TQFP PIN NO.	SYMBOL	PIN NAME	TQFP PIN NO.
A_0 - A_{18}	Address Inputs	32,33,34,35,36,37,43	V_{DD}	Power Supply(+3.3V)	15,41,65,91
		44,45,46,47,48,49,50	V_{SS}	Ground	17,40,67,90
		80,81,82,99,100	N.C.	No Connect	1,2,3,6,7,14,16,25,28,29,
$\overline{ADV}$	Burst Address Advance	83			30,38,39,42,51,52,53,56,
$\overline{ADSP}$	Address Status Processor	84			57,66,75,78,79,95,96
$\overline{ADSC}$	Address Status Controller	85			
CLK	Clock	89	DQa_0 ~ a_7	Data Inputs/Outputs	58,59,62,63,68,69,72,73
$\overline{CS_1}$	Chip Select	98	DQb_0 ~ b_7		8,9,12,13,18,19,22,23
$\overline{CS_2}$	Chip Select	97	DQPa, Pb		74,24
$\overline{CS_2}$	Chip Select	92	V_{DDQ}	Output Power Supply	4,11,20,27,54,61,70,77
$\overline{WE_x}$	Byte Write Inputs	93,94		(2.5V or 3.3V)	
$\overline{OE}$	Output Enable	86	V_{SSQ}	Output Ground	5,10,21,26,55,60,71,76
$\overline{GW}$	Global Write Enable	88			
$\overline{BW}$	Byte Write Enable	87			
$\overline{ZZ}$	Power Down Input	64			
LBO	Burst Mode Control	31			

Notes : 1. A_0 and A_1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.
2. The pin 42 is reserved for address bit for the 16Mb .

119BGA PACKAGE PIN CONFIGURATIONS(TOP VIEW)

Only for K7A803609B - HC20 (256Kx36)

	1	2	3	4	5	6	7
A	V_{DDQ}	A	A	$\overline{ADSP}$	A	A	V_{DDQ}
B	NC	CS_2	A	$\overline{ADSC}$	A	A	NC
C	NC	A	A	V_{DD}	A	A	NC
D	DQc	DQPc	V_{SS}	NC	V_{SS}	DQPb	DQb
E	DQc	DQc	V_{SS}	$\overline{CS_1}$	V_{SS}	DQb	DQb
F	V_{DDQ}	DQc	V_{SS}	$\overline{OE}$	V_{SS}	DQb	V_{DDQ}
G	DQc	DQc	$\overline{WE}$c	$\overline{ADV}$	$\overline{WE}$b	DQb	DQb
H	DQc	DQc	V_{SS}	$\overline{GW}$	V_{SS}	DQb	DQb
J	V_{DDQ}	V_{DD}	NC	V_{DD}	NC	V_{DD}	V_{DDQ}
K	DQd	DQd	V_{SS}	CLK	V_{SS}	DQa	DQa
L	DQd	DQd	$\overline{WE}$d	NC	$\overline{WE}$a	DQa	DQa
M	V_{DDQ}	DQd	V_{SS}	$\overline{BW}$	V_{SS}	DQa	V_{DDQ}
N	DQd	DQd	V_{SS}	A_1*	V_{SS}	DQa	DQa
P	DQd	DQPd	V_{SS}	A_0*	V_{SS}	DQPa	DQa
R	NC	A	$\overline{LBO}$	V_{DD}	NC	A	NC
T	NC	NC	A	A	A	NC	ZZ
U	V_{DDQ}	TMS	TDI	TCK	TDO	NC	V_{DDQ}

Note : * A_0 and A_1 are the two least significant bits(LSB) of the address field and set the internal burst counter if burst is desired.

PIN NAME

SYMBOL	PIN NAME	SYMBOL	PIN NAME
A	Address Inputs	V_{DD}	Power Supply(+3.3V)
A_0,A_1	Burst Count Address	V_{SS}	Ground
$\overline{ADV}$	Burst Address Advance	N.C.	No Connect
$\overline{ADSP}$	Address Status Processor		
$\overline{ADSC}$	Address Status Controller	DQa	Data Inputs/Outputs
CLK	Clock	DQb	Data Inputs/Outputs
$\overline{CS_1}$	Chip Select	DQc	Data Inputs/Outputs
CS_2	Chip Select	DQd	Data Inputs/Outputs
$\overline{WE}$x (x=a,b,c,d)	Byte Write Inputs	DQPa~Pd	Data Inputs/Outpus
		V_{DDQ}	Output Power Supply (2.5V or 3.3V)
$\overline{OE}$	Output Enable		
$\overline{GW}$	Global Write Enable		
$\overline{BW}$	Byte Write Enable		
$\overline{ZZ}$	Power Down Input		
$\overline{LBO}$	Burst Mode Control		
TCK	JTAG Test Clock		
TMS	JTAG Test Mode Select		
TDI	JTAG Test Data Input		
TDO	JTAG Test Data Output		

FUNCTION DESCRIPTION

The K7A803609B, K7A803209B and K7A801809B are synchronous SRAM designed to support the burst address accessing sequence of the Power PC based microprocessor. All inputs (with the exception of $\overline{OE}$, $\overline{LBO}$ and ZZ) are sampled on rising clock edges. The start and duration of the burst access is controlled by $\overline{ADSC}$, $\overline{ADSP}$ and $\overline{ADV}$ and chip select pins.

The accesses are enabled with the chip select signals and output enabled signals. Wait states are inserted into the access with $\overline{ADV}$.

When ZZ is pulled high, the SRAM will enter a Power Down State. At this time, internal state of the SRAM is preserved. When ZZ returns to low, the SRAM normally operates after 2cycles of wake up time. ZZ pin is pulled down internally.

Read cycles are initiated with $\overline{ADSP}$(regardless of $\overline{WE}$x and $\overline{ADSC}$)using the new external address clocked into the on-chip address register whenever $\overline{ADSP}$ is sampled low, the chip selects are sampled active, and the output buffer is enabled with $\overline{OE}$. In read operation the data of cell array accessed by the current address, registered in the Data-out registers by the positive edge of CLK, are carried to the Data-out buffer by the next positive edge of CLK. The data, registered in the Data-out buffer, are projected to the output pins. $\overline{ADV}$ is ignored on the clock edge that samples $\overline{ADSP}$ asserted, but is sampled on the subsequent clock edges. The address increases internally for the next access of the burst when $\overline{WE}$x are sampled High and $\overline{ADV}$ is sampled low. And $\overline{ADSP}$ is blocked to control signals by disabling $\overline{CS}_1$.

All byte write is done by $\overline{GW}$(regaedless of $\overline{BW}$ and $\overline{WE}$x.), and each byte write is performed by the combination of $\overline{BW}$ and $\overline{WE}$x when $\overline{GW}$ is high.

Write cycles are performed by disabling the output buffers with $\overline{OE}$ and asserting $\overline{WE}$x. $\overline{WE}$x are ignored on the clock edge that samples $\overline{ADSP}$ low, but are sampled on the subsequent clock edges. The output buffers are disabled when $\overline{WE}$x are sampled Low(regaedless of $\overline{OE}$). Data is clocked into the data input register when $\overline{WE}$x sampled Low. The address increases internally to the next address of burst, if both $\overline{WE}$x and $\overline{ADV}$ are sampled Low. Individual byte write cycles are performed by any one or more byte write enable signals($\overline{WE}$a, $\overline{WE}$b, $\overline{WE}$c or $\overline{WE}$d) sampled low. The $\overline{WE}$a control DQa_0 ~ DQa_7 and DQPa, $\overline{WE}$b controls DQb_0 ~ DQb_7 and DQPb, $\overline{WE}$c controls DQc_0 ~ DQc_7 and DQPc, and $\overline{WE}$d control DQd_0 ~ DQd_7 and DQPd. Read or write cycle may also be initiated with $\overline{ADSC}$, instead of $\overline{ADSP}$. The differences between cycles initiated with $\overline{ADSC}$ and $\overline{ADSP}$ as are follows;

- $\overline{ADSP}$ must be sampled high when $\overline{ADSC}$ is sampled low to initiate a cycle with $\overline{ADSC}$.
- $\overline{WE}$x are sampled on the same clock edge that sampled $\overline{ADSC}$ low(and $\overline{ADSP}$ high).

Addresses are generated for the burst access as shown below, The starting point of the burst sequence is provided by the external address. The burst address counter wraps around to its initial state upon completion. The burst sequence is determined by the state of the $\overline{LBO}$ pin. When this pin is Low, linear burst sequence is selected. When this pin is High, Interleaved burst sequence is selected.

BURST SEQUENCE TABLE

(Interleaved Burst)

$\overline{LBO}$ PIN	HIGH	Case 1		Case 2		Case 3		Case 4	
		A_1	A_0	A_1	A_0	A_1	A_0	A_1	A_0
First Address		0	0	0	1	1	0	1	1
↓		0	1	0	0	1	1	1	0
		1	0	1	1	0	0	0	1
Fourth Address		1	1	1	0	0	1	0	0

(Linear Burst)

$\overline{LBO}$ PIN	LOW	Case 1		Case 2		Case 3		Case 4	
		A_1	A_0	A_1	A_0	A_1	A_0	A_1	A_0
First Address		0	0	0	1	1	0	1	1
↓		0	1	1	0	1	1	0	0
		1	0	1	1	0	0	0	1
Fourth Address		1	1	0	0	0	1	1	0

Note : 1. $\overline{LBO}$ pin must be tied to High or Low, and Floating State must not be allowed.

ASYNCHRONOUS TRUTH TABLE

OPERATION	ZZ	$\overline{OE}$	I/O STATUS
Sleep Mode	H	X	High-Z
Read	L	L	DQ
	L	H	High-Z
Write	L	X	Din, High-Z
Deselected	L	X	High-Z

Notes

1. X means "Don't Care".
2. ZZ pin is pulled down internally
3. For write cycles that following read cycles, the output buffers must be disabled with $\overline{OE}$, otherwise data bus contention will occur.
4. Sleep Mode means power down state of which stand-by current does not depend on cycle time.
5. Deselected means power down state of which stand-by current depends on cycle time.

TRUTH TABLES

SYNCHRONOUS TRUTH TABLE

$\overline{CS_1}$	CS_2	$\overline{CS_2}$	$\overline{ADSP}$	$\overline{ADSC}$	$\overline{ADV}$	$\overline{WRITE}$	CLK	ADDRESS ACCESSED	OPERATION
H	X	X	X	L	X	X	↑	N/A	Not Selected
L	L	X	L	X	X	X	↑	N/A	Not Selected
L	X	H	L	X	X	X	↑	N/A	Not Selected
L	L	X	X	L	X	X	↑	N/A	Not Selected
L	X	H	X	L	X	X	↑	N/A	Not Selected
L	H	L	L	X	X	X	↑	External Address	Begin Burst Read Cycle
L	H	L	H	L	X	L	↑	External Address	Begin Burst Write Cycle
L	H	L	H	L	X	H	↑	External Address	Begin Burst Read Cycle
X	X	X	H	H	L	H	↑	Next Address	Continue Burst Read Cycle
H	X	X	X	H	L	H	↑	Next Address	Continue Burst Read Cycle
X	X	X	H	H	L	L	↑	Next Address	Continue Burst Write Cycle
H	X	X	X	H	L	L	↑	Next Address	Continue Burst Write Cycle
X	X	X	H	H	H	H	↑	Current Address	Suspend Burst Read Cycle
H	X	X	X	H	H	H	↑	Current Address	Suspend Burst Read Cycle
X	X	X	H	H	H	L	↑	Current Address	Suspend Burst Write Cycle
H	X	X	X	H	H	L	↑	Current Address	Suspend Burst Write Cycle

NOTE : 1. X means "Don't Care". 2. The rising edge of clock is symbolized by ↑.

3. $\overline{WRITE}$ = L means Write operation in WRITE TRUTH TABLE.
   $\overline{WRITE}$ = H means Read operation in WRITE TRUTH TABLE.

4. Operation finally depends on status of asynchronous input pins(ZZ and $\overline{OE}$).

WRITE TRUTH TABLE(x36/32)

$\overline{GW}$	$\overline{BW}$	$\overline{WEa}$	$\overline{WEb}$	$\overline{WEc}$	$\overline{WEd}$	OPERATION
H	H	X	X	X	X	READ
H	L	H	H	H	H	READ
H	L	L	H	H	H	WRITE BYTE a
H	L	H	L	H	H	WRITE BYTE b
H	L	H	H	L	L	WRITE BYTE c and d
H	L	L	L	L	L	WRITE ALL BYTEs
L	X	X	X	X	X	WRITE ALL BYTEs

Notes : 1. X means "Don't Care".

2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

WRITE TRUTH TABLE(x18)

$\overline{GW}$	$\overline{BW}$	$\overline{WEa}$	$\overline{WEb}$	OPERATION
H	H	X	X	READ
H	L	H	H	READ
H	L	L	H	WRITE BYTE a
H	L	H	L	WRITE BYTE b
H	L	L	L	WRITE ALL BYTEs
L	X	X	X	WRITE ALL BYTEs

Notes : 1. X means "Don't Care".

2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

ABSOLUTE MAXIMUM RATINGS*

PARAMETER		SYMBOL	RATING	UNIT
Voltage on V_{DD} Supply Relative to V_{SS}		V_{DD}	-0.3 to 4.6	V
Voltage on V_{DDQ} Supply Relative to V_{SS}		V_{DDQ}	V_{DD}	V
Voltage on Input Pin Relative to V_{SS}		V_{IN}	-0.3 to V_{DD}+0.3	V
Voltage on I/O Pin Relative to V_{SS}		V_{IO}	-0.3 to V_{DDQ}+0.3	V
Power Dissipation		P_D	1.6	W
Storage Temperature		T_{STG}	-65 to 150	°C
Operating Temperature	Commercial	T_{OPR}	0 to 70	°C
	Industrial	T_{OPR}	-40 to 85	°C
Storage Temperature Range Under Bias		T_{BIAS}	-10 to 85	°C

***Note :** Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING CONDITIONS at 3.3V I/O(0°C ≤ T_A ≤ 70°C)

PARAMETER	SYMBOL	MIN	Typ.	MAX	UNIT
Supply Voltage	V_{DD}	3.135	3.3	3.465	V
	V_{DDQ}	3.135	3.3	3.465	V
Ground	V_{SS}	0	0	0	V

* The above parameters are also guaranteed at industrial temperature range.

OPERATING CONDITIONS at 2.5V I/O(0°C ≤ T_A ≤ 70°C)

PARAMETER	SYMBOL	MIN	Typ.	MAX	UNIT
Supply Voltage	V_{DD}	3.135	3.3	3.465	V
	V_{DDQ}	2.375	2.5	2.9	V
Ground	V_{SS}	0	0	0	V

* The above parameters are also guaranteed at industrial temperature range.

CAPACITANCE*(T_A=25°C, f=1MHz)

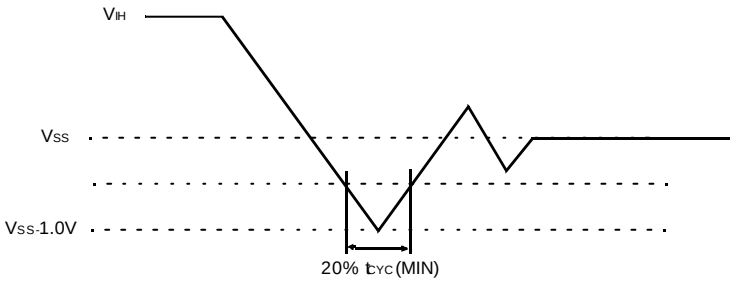
PARAMETER	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Input Capacitance	C_{IN}	V_{IN}=0V	-	5	pF
Output Capacitance	C_{OUT}	V_{OUT}=0V	-	7	pF

***Note :** Sampled not 100% tested.

DC ELECTRICAL CHARACTERISTICS (V_{DD}=3.3V+0.165V/-0.165V, T_A=0°C to +70°C)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	MAX	UNIT	NOTES
Input Leakage Current(except ZZ)	I_{IL}	V_{DD} = Max ; V_{IN}=V_{SS} to V_{DD}		-2	+2	µA	
Output Leakage Current	I_{OL}	Output Disabled, V_{OUT}=V_{SS} to V_{DDQ}		-2	+2	µA	
Operating Current	I_{CC}	Device Selected, I_{OUT}=0mA, ZZ≤V_{IL}, Cycle Time ≥ t_{CYC} Min	-25	-	470	mA	1,2
			-20	-	400		
Standby Current	I_{SB}	Device deselected, I_{OUT}=0mA, ZZ≤V_{IL}, f=Max, All Inputs≤0.2V or ≥V_{DD}-0.2V	-25	-	170	mA	
			-20	-	150		
	I_{SB1}	Device deselected, I_{OUT}=0mA, ZZ≤0.2V, f = 0, All Inputs=fixed (V_{DD}-0.2V or 0.2V)		-	100	mA	
	I_{SB2}	Device deselected, I_{OUT}=0mA, ZZ≥V_{DD}-0.2V, f=Max, All Inputs≤V_{IL} or ≥V_{IH}		-	60	mA	
Output Low Voltage(3.3V I/O)	V_{OL}	I_{OL}=8.0mA		-	0.4	V	
Output High Voltage(3.3V I/O)	V_{OH}	I_{OH}=-4.0mA		2.4	-	V	
Output Low Voltage(2.5V I/O)	V_{OL}	I_{OL}=1.0mA		-	0.4	V	
Output High Voltage(2.5V I/O)	V_{OH}	I_{OH}=-1.0mA		2.0	-	V	
Input Low Voltage(3.3V I/O)	V_{IL}			-0.3*	0.8	V	
Input High Voltage(3.3V I/O)	V_{IH}			2.0	V_{DD}+0.3	V	3
Input Low Voltage(2.5V I/O)	V_{IL}			-0.3*	0.7	V	
Input High Voltage(2.5V I/O)	V_{IH}			1.7	V_{DD}+0.3	V	3

Notes : The above parameters are also guaranteed at industrial temperature range.
1. Reference AC Operating Conditions and Characteristics for input and timing.
2. Data states are all zero.
3. In Case of I/O Pins, the Max. V_{IH}=V_{DDQ}+0.3V.

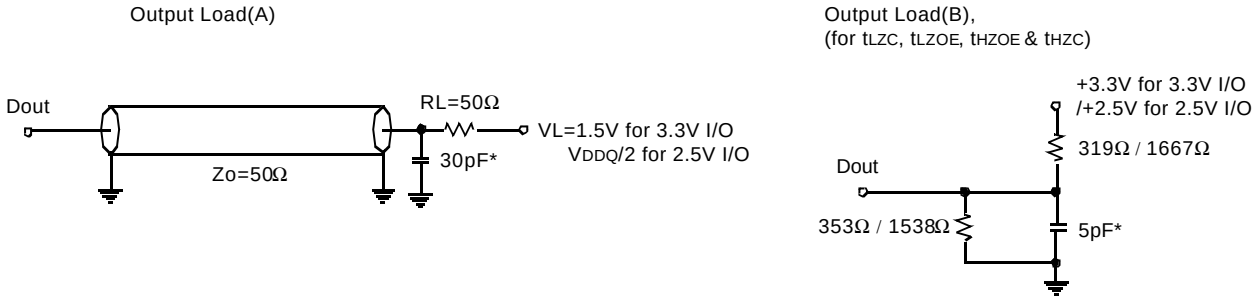


TEST CONDITIONS

(V_{DD}=3.3V+0.165V/-0.165V,V_{DDQ}=3.3V+0.165/-0.165V or V_{DD}=3.3V+0.165V/-0.165V,V_{DDQ}=2.5V+0.4V/-0.125V, T_A=0to70°C)

Parameter	Value
Input Pulse Level(for 3.3V I/O)	0 to 3.0V
Input Pulse Level(for 2.5V I/O)	0 to 2.5V
Input Rise and Fall Time(Measured at 20% to 80% for 3.3V I/O)	1.0V/ns
Input Rise and Fall Time(Measured at 20% to 80% for 2.5V I/O)	1.0V/ns
Input and Output Timing Reference Levels for 3.3V I/O	1.5V
Input and Output Timing Reference Levels for 2.5V I/O	V_{DDQ}/2
Output Load	See Fig. 1

* The above parameters are also guaranteed at industrial temperature range.



* Including Scope and Jig Capacitance

Fig. 1

AC TIMING CHARACTERISTICS(V_{DD}=3.3V+0.165V/-0.165V, T_A=0°C to +70°C)

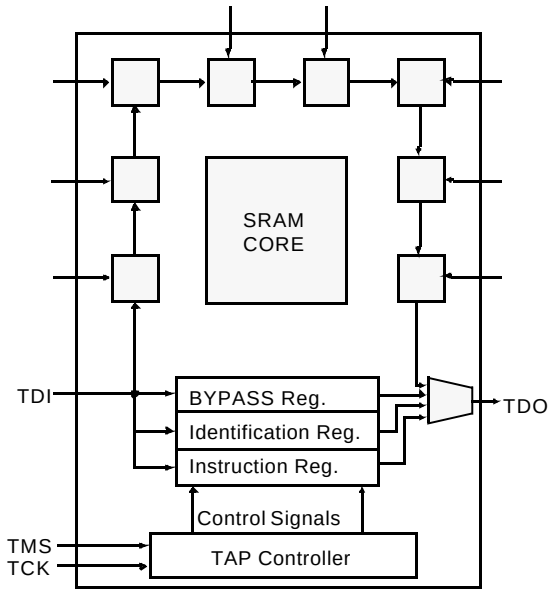
PARAMETER	Symbol	-25		-20		UNIT
		MIN	MAX	MIN	MAX	
Cycle Time	t_{CYC}	4.0	-	5.0	-	ns
Clock Access Time	t_{CD}	-	2.6	-	3.1	ns
Output Enable to Data Valid	t_{OE}	-	2.6	-	3.1	ns
Clock High to Output Low-Z	t_{LZC}	0	-	0	-	ns
Output Hold from Clock High	t_{OH}	0.8	-	1.0	-	ns
Output Enable Low to Output Low-Z	t_{LZOE}	0	-	0	-	ns
Output Enable High to Output High-Z	t_{HZOE}	-	2.6	-	3.0	ns
Clock High to Output High-Z	t_{HZC}	0.8	2.6	1.0	3.0	ns
Clock High Pulse Width	t_{CH}	1.7	-	2.0	-	ns
Clock Low Pulse Width	t_{CL}	1.7	-	2.0	-	ns
Address Setup to Clock High	t_{AS}	1.2	-	1.4	-	ns
Address Status Setup to Clock High	t_{SS}	1.2	-	1.4	-	ns
Data Setup to Clock High	t_{DS}	1.2	-	1.4	-	ns
Write Setup to Clock High ($\overline{GW}$, $\overline{BW}$, $\overline{WE_X}$)	t_{WS}	1.2	-	1.4	-	ns
Address Advance Setup to Clock High	t_{ADVS}	1.2	-	1.4	-	ns
Chip Select Setup to Clock High	t_{CSS}	1.2	-	1.4	-	ns
Address Hold from Clock High	t_{AH}	0.3	-	0.4	-	ns
Address Status Hold from Clock High	t_{SH}	0.3	-	0.4	-	ns
Data Hold from Clock High	t_{DH}	0.3	-	0.4	-	ns
Write Hold from Clock High ($\overline{GW}$, $\overline{BW}$, $\overline{WE_X}$)	t_{WH}	0.3	-	0.4	-	ns
Address Advance Hold from Clock High	t_{ADVH}	0.3	-	0.4	-	ns
Chip Select Hold from Clock High	t_{CSH}	0.3	-	0.4	-	ns
ZZ High to Power Down	t_{PDS}	2	-	2	-	cycle
ZZ Low to Power Up	t_{PUS}	2	-	2	-	cycle

Notes : 1.The above parameters are also guaranteed at industrial temperature range.
2. All address inputs must meet the specified setup and hold times for all rising clock edges whenever $\overline{ADSC}$ and/or $\overline{ADSP}$ is sampled low and $\overline{CS}$ is sampled low. All other synchronous inputs must meet the specified setup and hold times whenever this device is chip selected.
3. Both chip selects must be active whenever $\overline{ADSC}$ or $\overline{ADSP}$ is sampled low in order for the this device to remain enabled.
4. $\overline{ADSC}$ or $\overline{ADSP}$ must not be asserted for at least 2 Clock after leaving ZZ state.

IEEE 1149.1 TEST ACCESS PORT AND BOUNDARY SCAN-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port(TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. Internal data is not driven out of the SRAM under JTAG control. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction Register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up, therefore, TRST signal is not required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to V_{SS} to preclude mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected. But they may also be tied to V_{DD} through a resistor. TDO should be left unconnected.

JTAG Block Diagram



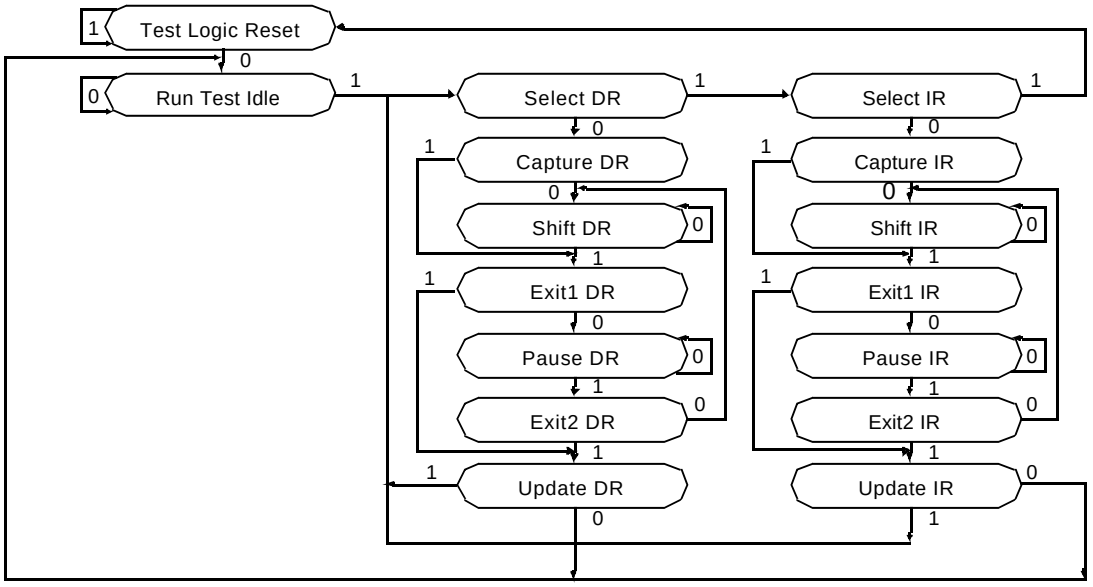
JTAG Instruction Coding

IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	EXTEST	Boundary Scan Register	1
0	0	1	IDCODE	Identification Register	3
0	1	0	SAMPLE-Z	Boundary Scan Register	2
0	1	1	BYPASS	Bypass Register	4
1	0	0	SAMPLE	Boundary Scan Register	5
1	0	1	RESERVED	Do Not Use	6
1	1	0	BYPASS	Bypass Register	4
1	1	1	BYPASS	Bypass Register	4

NOTE :

1. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs. This instruction is not IEEE 1149.1 compliant.
2. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs.
3. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.
4. Bypass register is initiated to V_{SS} when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when exiting the Shift DR states.
5. SAMPLE instruction dose not places DQs in Hi-Z.
6. This instruction is reserved for future use.

TAP Controller State Diagram



SCAN REGISTER DEFINITION

Part	Instruction Register	Bypass Register	ID Register	Boundary Scan
256Kx36	3 bits	1 bits	32 bits	70 bits
512Kx18	3 bits	1 bits	32 bits	70 bits

ID REGISTER DEFINITION

Part	Revision Number (31:28)	Part Configuration (27:18)	Vendor Definition (17:12)	Samsung JEDEC Code (11: 1)	Start Bit(0)
256Kx36	0000	00110 00100	XXXXXX	00001001110	1
512Kx18	0000	00111 00011	XXXXXX	00001001110	1

119BGA BOUNDARY SCAN EXIT ORDER(x36)

36	4B	$\overline{ADSC}$		$\overline{OE}$	4F	35
37	4E	$\overline{CS_1}$		$\overline{ADV}$	4G	34
38	4H	$\overline{GW}$		CLK	4K	33
39	3G	$\overline{WEc}$		$\overline{BW}$	4M	32
40	3C	A		$\overline{ADSP}$	4A	31
41	3B	A		$\overline{WEb}$	5G	30
42	3A	A		A	5C	29
43	2B	CS2		A	5B	28
44	2C	A		A	5A	27
45	2A	A		A	6B	26
46	2D	DQPc		A	6A	25
47	1E	DQc		A	6C	24
48	2F	DQc		DQPb	6D	23
49	1G	DQc		DQb	6E	22
50	2H	DQc		DQb	6G	21
51	1D	DQc		DQb	7H	20
52	2E	DQc		DQb	7D	19
53	2G	DQc		DQb	7E	18
54	1H	DQc		DQb	6F	17
55	2K	DQd		DQb	7G	16
56	1L	DQd		DQb	6H	15
57	2M	DQd		DQa	7K	14
58	1N	DQd		DQa	6L	13
59	1P	DQd		DQa	6N	12
60	1K	DQd		DQa	7P	11
61	2L	DQd		DQa	6K	10
62	2N	DQd		DQa	7L	9
63	2P	DQPd		DQa	6M	8
64	3R	$\overline{LBO}$		DQa	7N	7
65	3L	$\overline{WEd}$		DQPa	6P	6
66	2R	A		ZZ	7T	5
67	3T	A		A	6R	4
68	4N	A1		$\overline{WEa}$	5L	3
69	4P	A0		A	5T	2
70	2T	NC		A	4T	1

119BGA BOUNDARY SCAN EXIT ORDER(x18)

36	4B	$\overline{ADSC}$		$\overline{OE}$	4F	35
37	4E	$\overline{CS_1}$		$\overline{ADV}$	4G	34
38	4H	$\overline{GW}$		CLK	4K	33
39	3G	$\overline{WEb}$		$\overline{BW}$	4M	32
40	3C	A		$\overline{ADSP}$	4A	31
41	3B	A		NC	5G	30
42	3A	A		A	5C	29
43	2B	CS2		A	5B	28
44	2C	A		A	5A	27
45	2A	A		A	6B	26
46	2D	NC		A	6A	25
47	1E	NC		A	6C	24
48	2F	NC		NC	7D	23
49	1G	NC		NC	6E	22
50	2H	NC		NC	6G	21
51	1D	DQb		NC	7H	20
52	2E	DQb		DQPa	6D	19
53	2G	DQb		DQa	7E	18
54	1H	DQb		DQa	6F	17
55	2K	DQb		DQa	7G	16
56	1L	DQb		DQa	6H	15
57	2M	DQb		DQa	7K	14
58	1N	DQb		DQa	6L	13
59	2P	DQPb		DQa	6N	12
60	1K	NC		DQa	7P	11
61	2L	NC		NC	6K	10
62	2N	NC		NC	7L	9
63	1P	NC		NC	6M	8
64	3R	$\overline{LBO}$		NC	7N	7
65	3L	NC		NC	6P	6
66	2R	A		ZZ	7T	5
67	3T	A		A	6R	4
68	4N	A1		$\overline{WEa}$	5L	3
69	4P	A0		A	5T	2
70	2T	A		A	6T	1

NOTE : 1. NC ; Don' t care.
2. 119BGA is Only Supported with K7A801800B-HC16, K7A803600B-HC16 and K7A803609B-HC20.

JTAG DC OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit	Note
Power Supply Voltage	V_{DD}	3.135	3.3	3.465	V	
Input High Level (3.3V I/O / 2.5V I/O)	V_{IH}	2.0 / 1.7	-	V_{DD}+0.3	V	1
Input Low Level (3.3V I/O / 2.5V I/O)	V_{IL}	-0.3	-	0.8 / 0.7	V	
Output High Voltage (3.3V I/O / 2.5V I/O)	V_{OH}	2.4 / 2.0	-	-	V	
Output Low Voltage (3.3V I/O / 2.5V I/O)	V_{OL}	-	-	0.4 / 0.4	V	

NOTE : The input level of SRAM pin is to follow the SRAM DC specification.

1. In Case of I/O Pins, the Max. $V_{IH}=V_{DDQ}$+0.3V

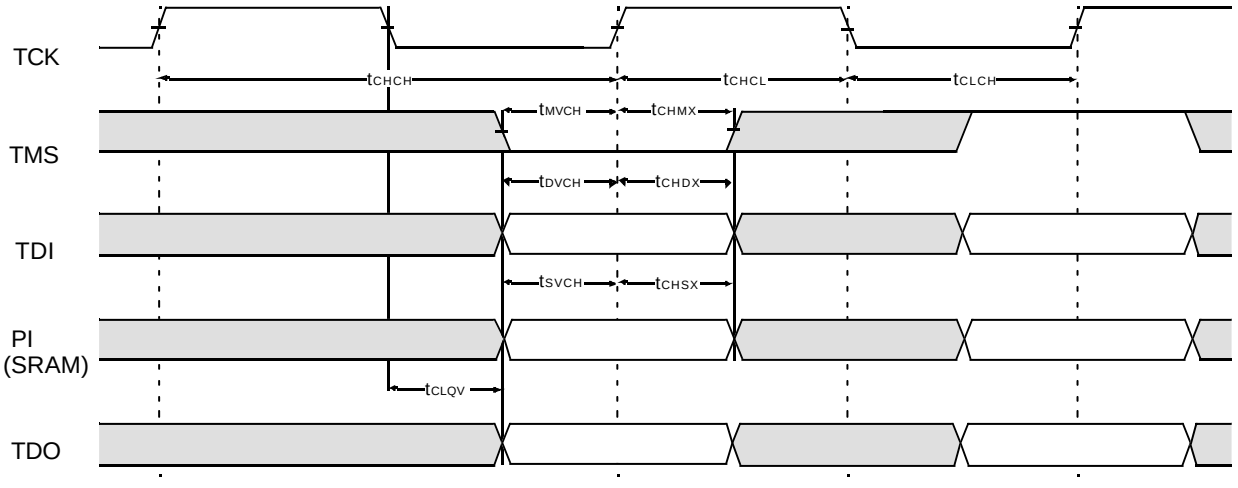
JTAG AC TEST CONDITIONS

Parameter	Symbol	Min	Unit	Note
Input High/Low Level (3.3V I/O / 2.5V I/O)	V_{IH}/V_{IL}	3.0 / 0 , 2.5 / 0	V	
Input Rise/Fall Time (3.3V I/O / 2.5V I/O)	TR/TF	1.0 / 1.0 , 1.0 /1 .0	ns	
Input and Output Timing Reference Level		$V_{DDQ}/2$	V	

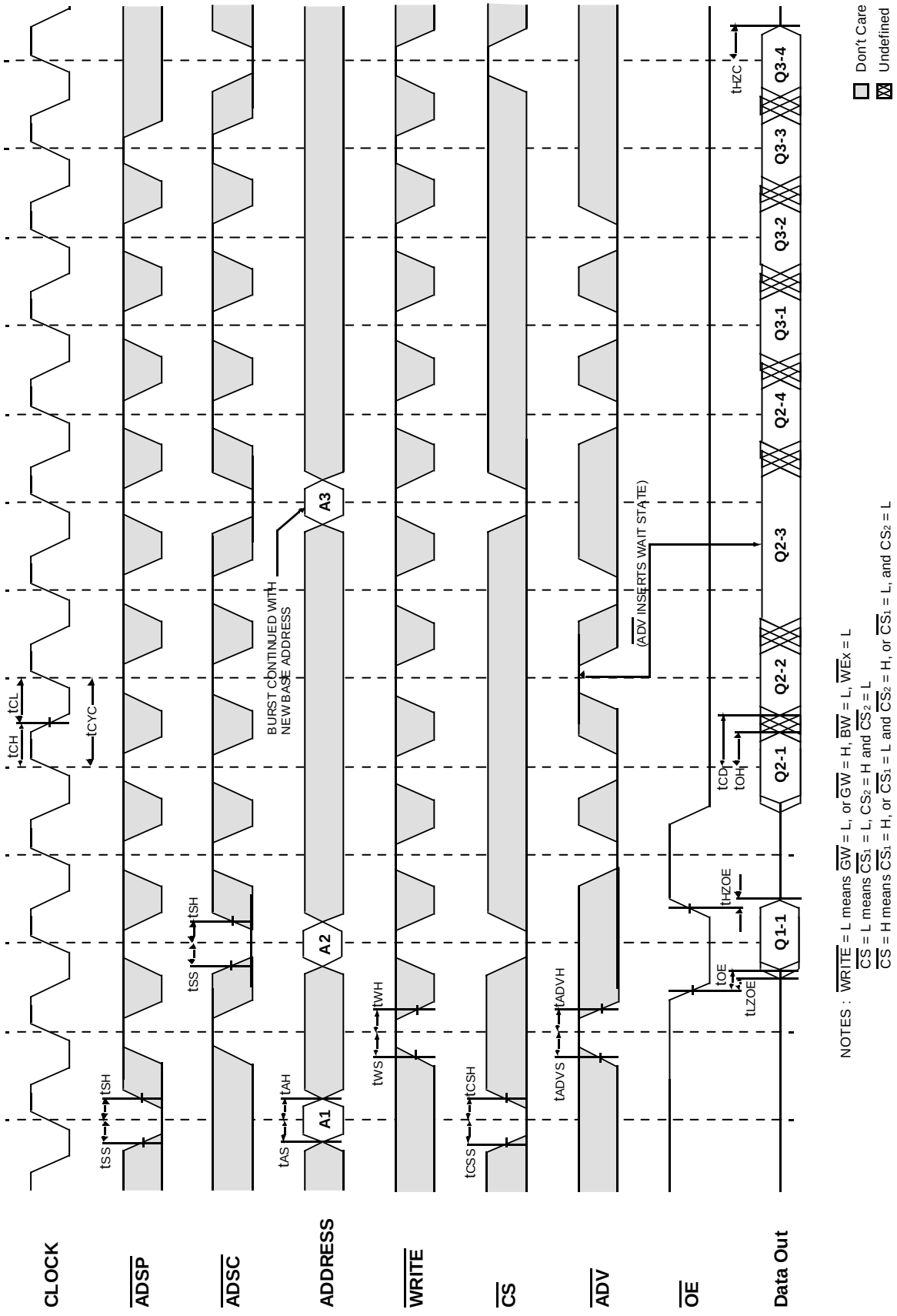
JTAG AC Characteristics

Parameter	Symbol	Min	Max	Unit	Note
TCK Cycle Time	t_{CHCH}	50	-	ns	
TCK High Pulse Width	t_{CHCL}	20	-	ns	
TCK Low Pulse Width	t_{CLCH}	20	-	ns	
TMS Input Setup Time	t_{MVCH}	5	-	ns	
TMS Input Hold Time	t_{CHMX}	5	-	ns	
TDI Input Setup Time	t_{DVCH}	5	-	ns	
TDI Input Hold Time	t_{CHDX}	5	-	ns	
SRAM Input Setup Time	t_{SVCH}	5	-	ns	
SRAM Input Hold Time	t_{CHSX}	5	-	ns	
Clock Low to Output Valid	t_{CLQV}	0	10	ns	

JTAG TIMING DIAGRAM

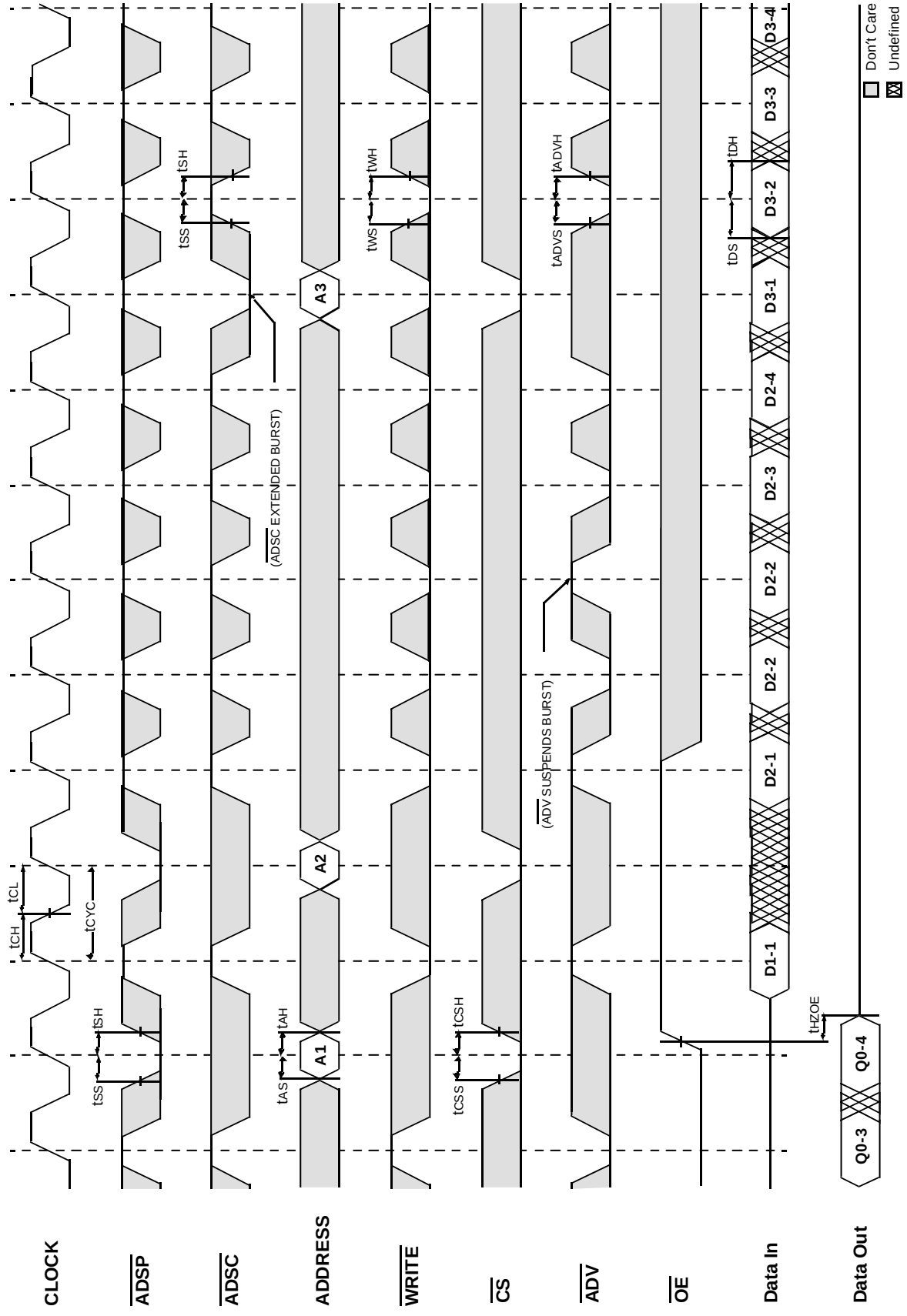


TIMING WAVEFORM OF READ CYCLE

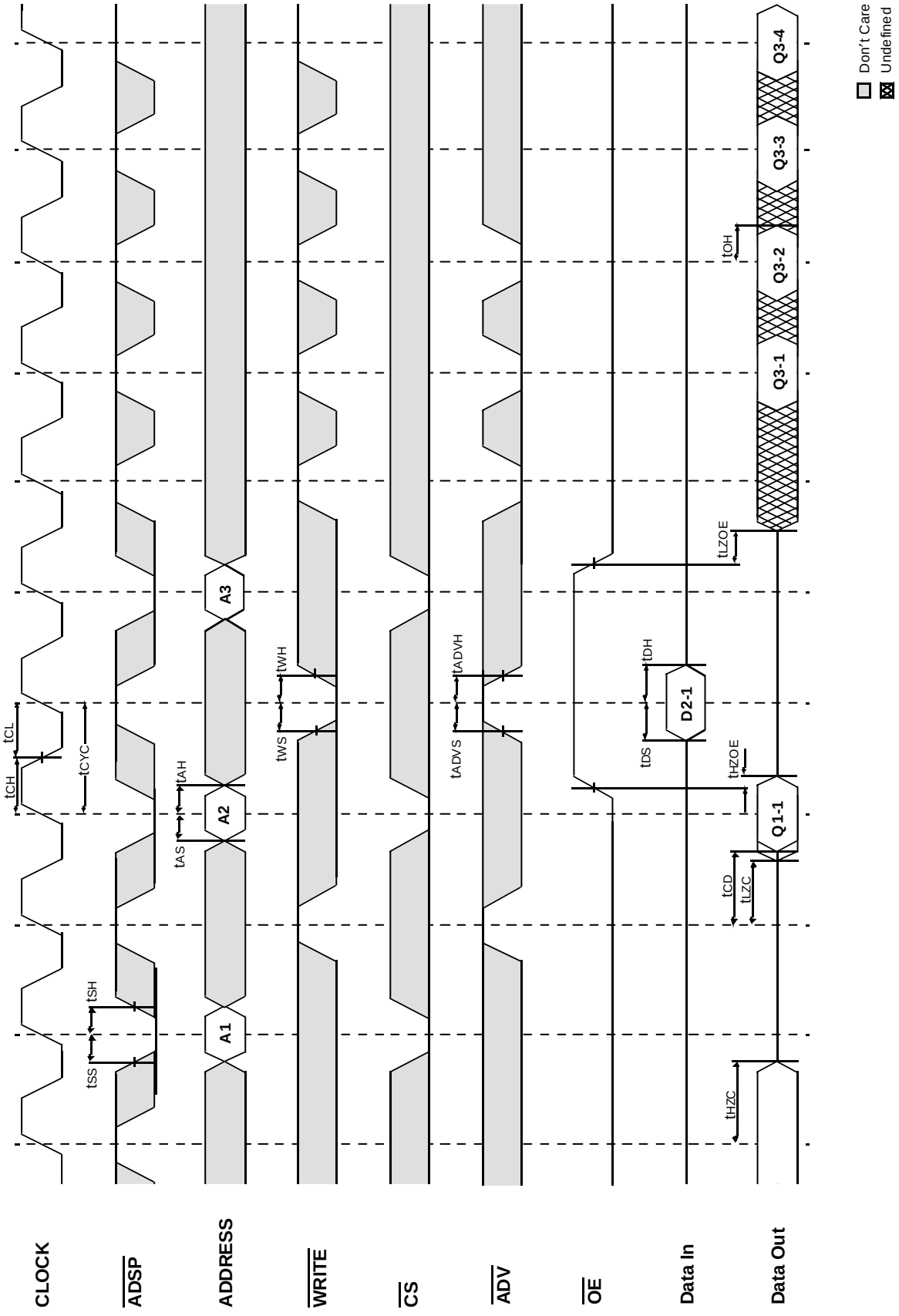


NOTES : WRITE = L means GW = L, or GW = H, BW = L, WEx = L
CS = L means CS1 = L, CS2 = H and CS2 = L
CS = H means CS1 = H, or CS1 = L and CS2 = H, or CS1 = L, and CS2 = L

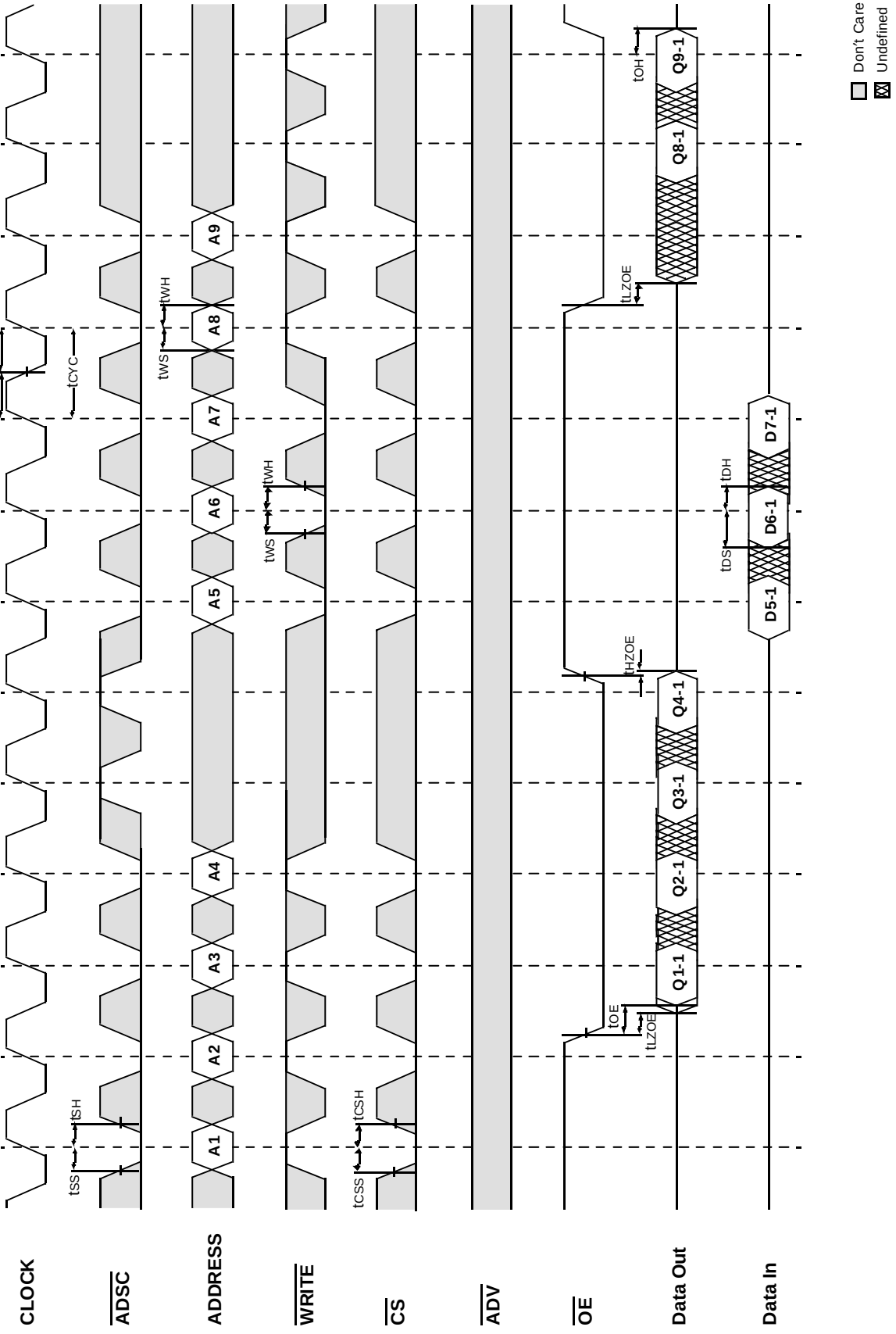
TIMING WAVEFORM OF WRTE CYCLE



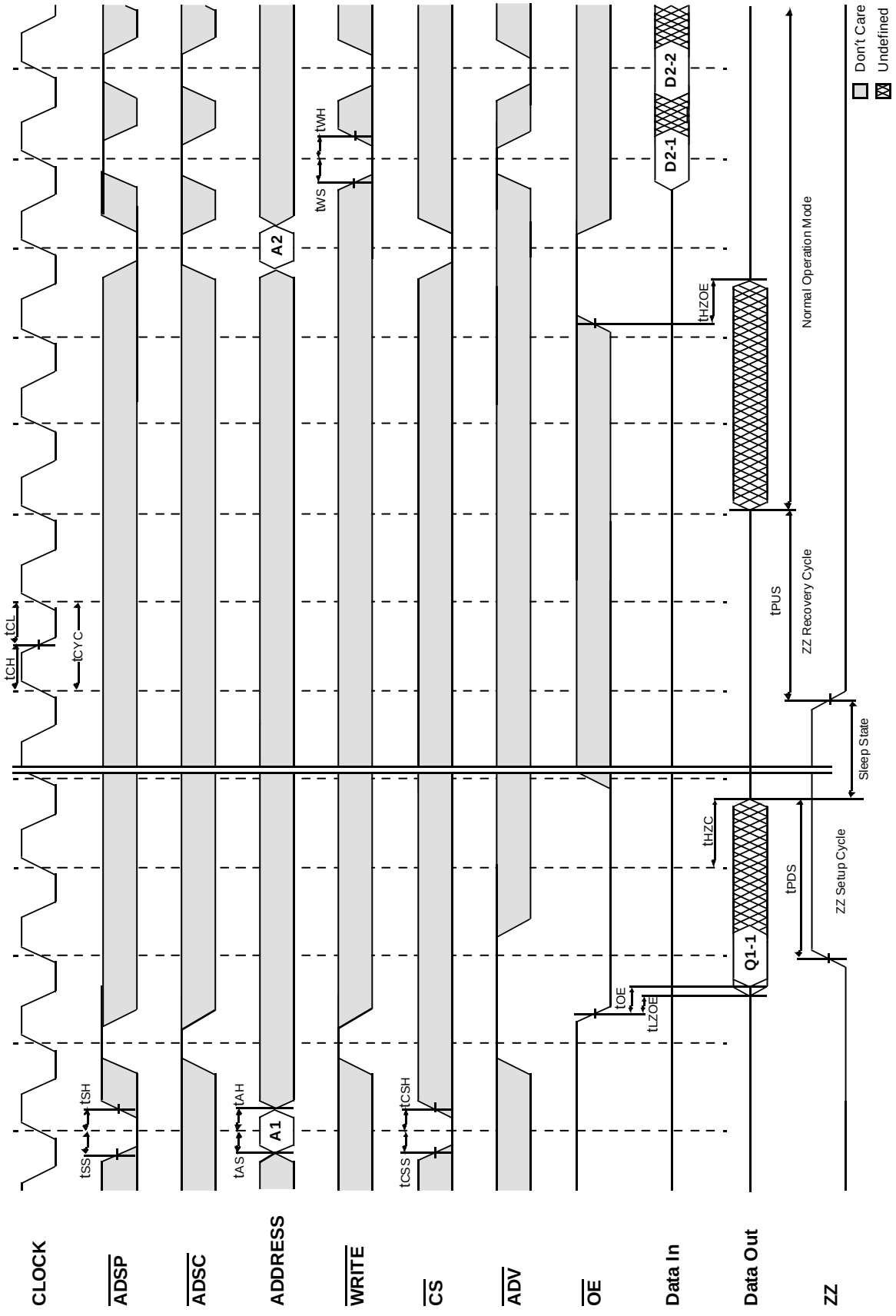
TIMING WAVEFORM OF COMBINATION READ/WRTE CYCLE(ADSP CONTROLLED , ADSC=HIGH)



TIMING WAVEFORM OF SINGLE READ/WRITE CYCLE($\overline{ADSC}$ CONTROLLED , $\overline{ADSP}$=HIGH)



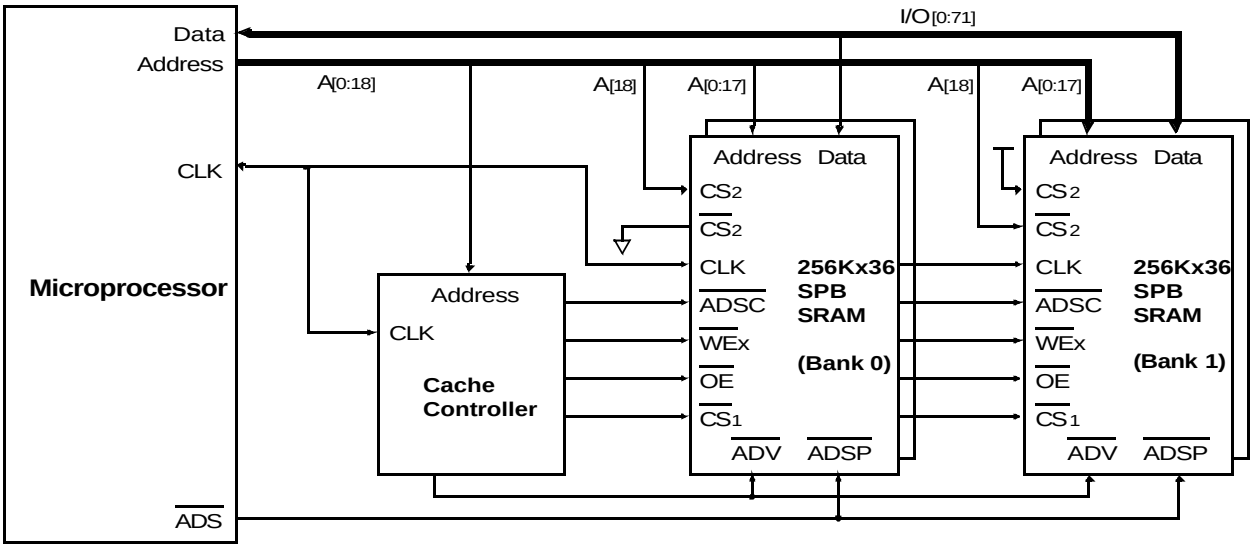
TIMING WAVEFORM OF POWER DOWN CYCLE



APPLICATION INFORMATION

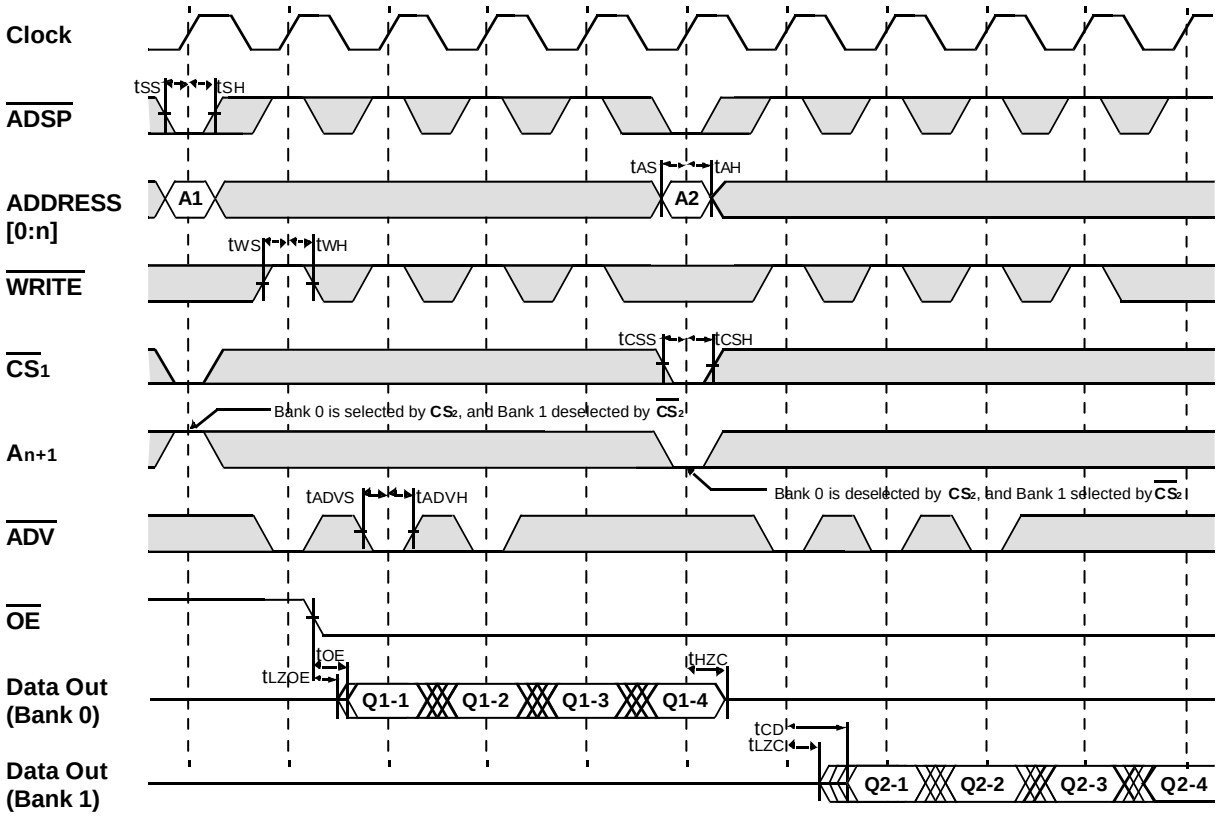
DEPTH EXPANSION

The Samsung 256Kx36 Synchronous Pipelined Burst SRAM has two additional chip selects for simple depth expansion. This permits easy secondary cache upgrades from 256K depth to 512K depth without extra logic.



INTERLEAVE READ TIMING (Refer to non-interleave write timing for interleave write timing)

(ADSP CONTROLLED , ADSC=HIGH)



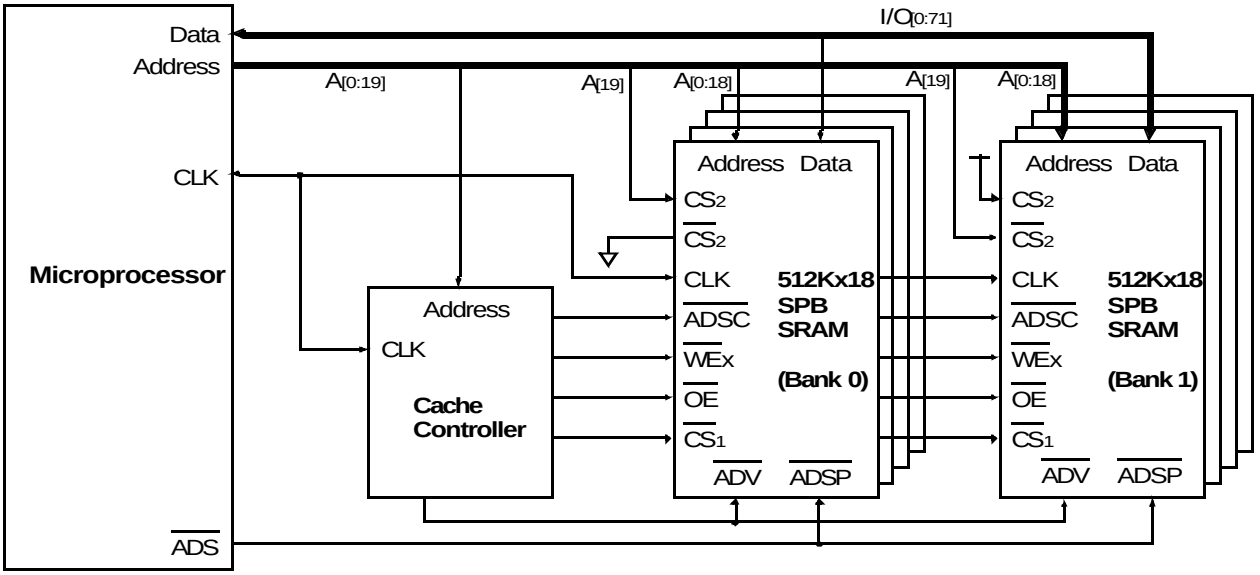
***Notes :** n = 14 32K depth , 15 64K depth
16 128K depth , 17 256K depth
18 512K depth

Don't Care Undefined

APPLICATION INFORMATION

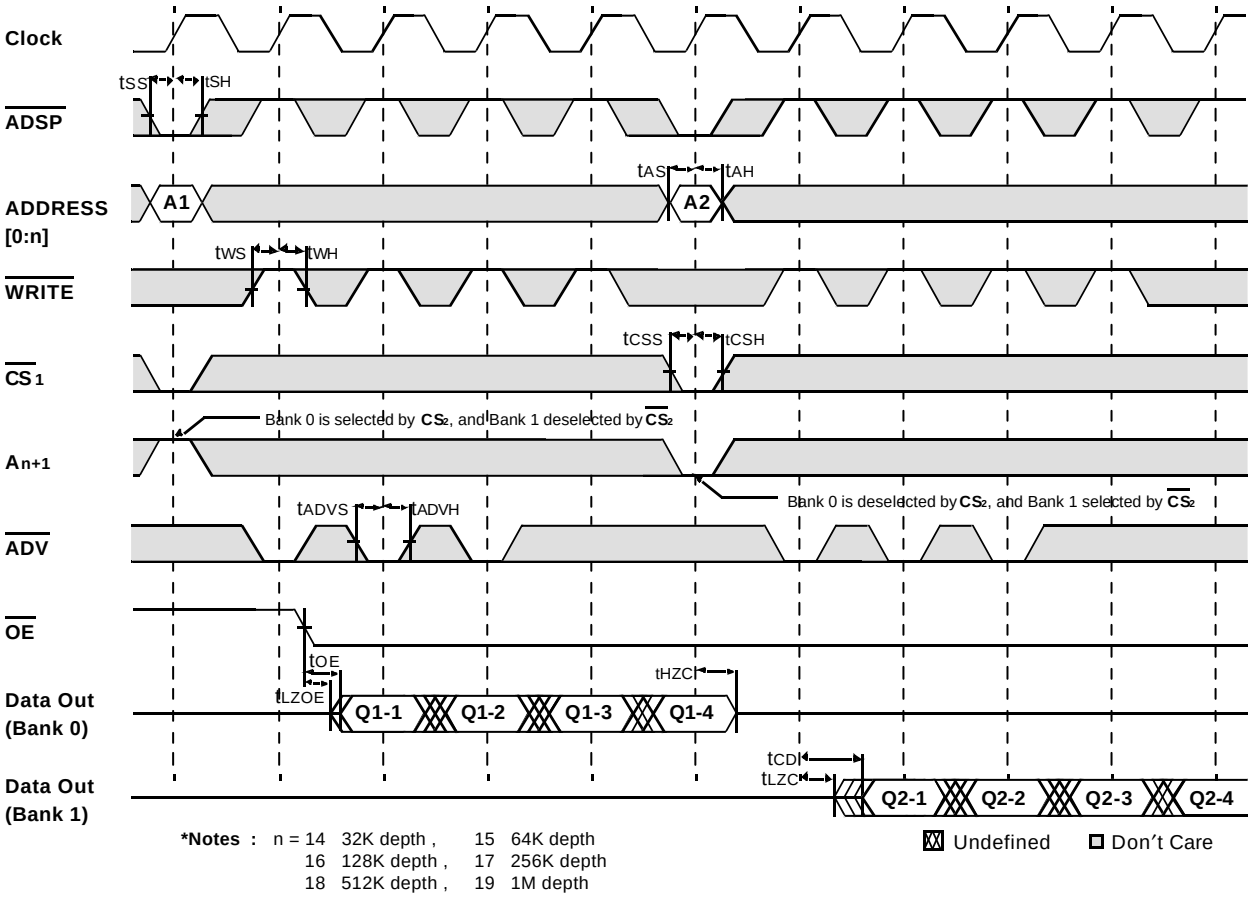
DEPTH EXPANSION

The Samsung 512Kx18 Synchronous Pipelined Burst SRAM has two additional chip selects for simple depth expansion. This permits easy secondary cache upgrades from 512K depth to 1M depth without extra logic.



INTERLEAVE READ TIMING (Refer to non-interleave write timing for interleave write timing)

(ADSP CONTROLLED , ADSC=HIGH)

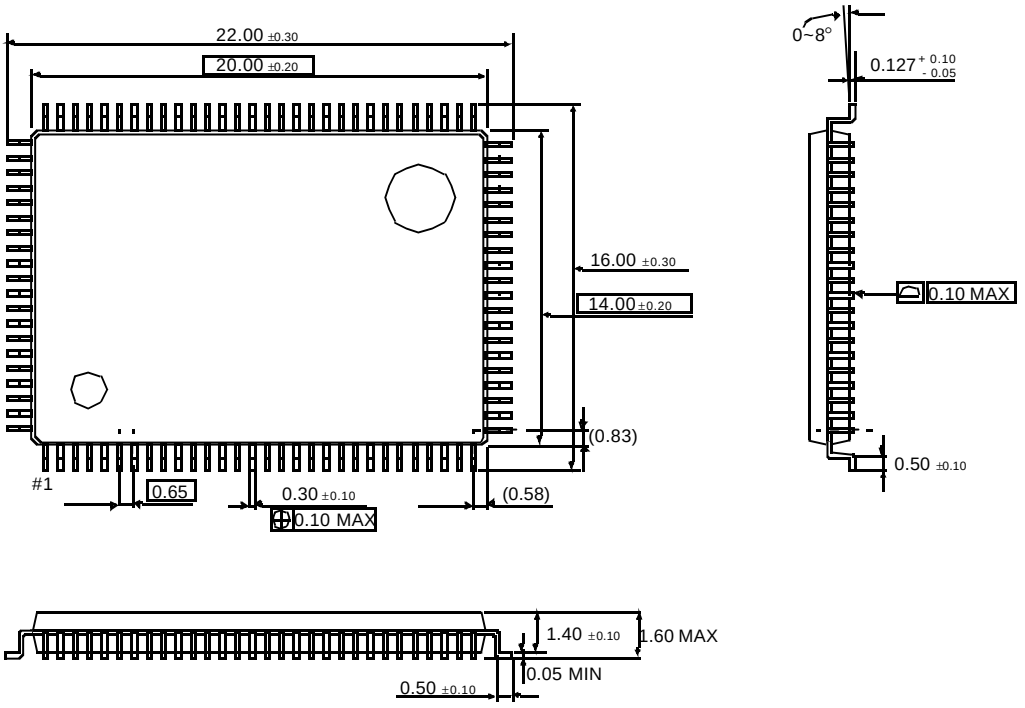


***Notes :** n = 14 32K depth , 15 64K depth
16 128K depth , 17 256K depth
18 512K depth , 19 1M depth

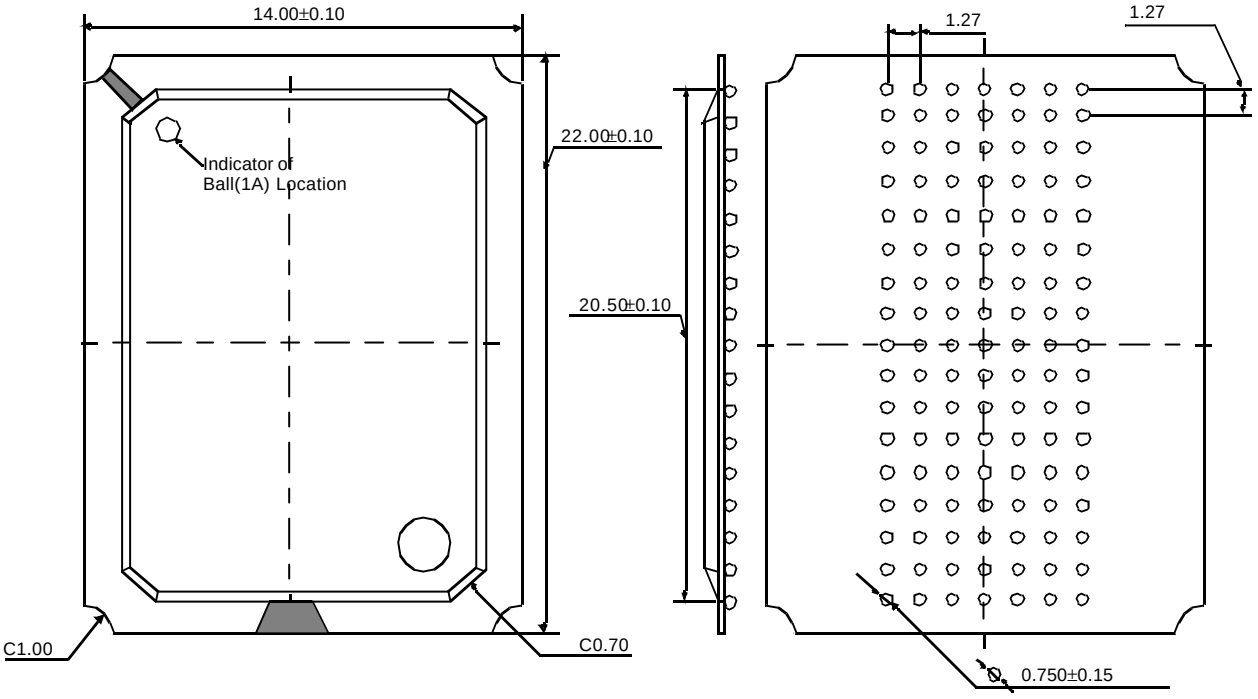
PACKAGE DIMENSIONS

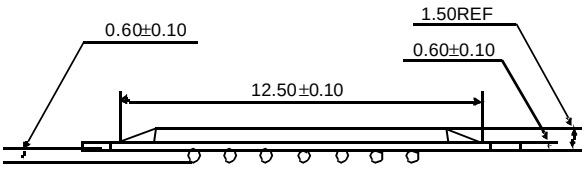
100-TQFP-1420A

Units ; millimeters/Inches



119BGA PACKAGE DIMENSIONS





Notes
1. All Dimensions are in Millimeters.
2. Solder Ball to PCB Offset : 0.10 Max.
3. PCB to Cavity Offset : 0.10 Max.

NOTE : 119BGA is Only Supported with K7A801800B-HC16, K7A803600B-HC16 and K7A803609B-HC20.